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ABSTRACT

The present invention relates to a process for
5 coating a surface of a substrate with a seed film of a
metallic material, the said surface being an
electrically conductive or semiconductive surface and
having recesses and/or projections. The process
comprises the following: an organic film is placed on
10 the said surface, the said film having a thickness such
that the free face of this film conformally follows the
recesses and/or projections of the said electrically
conductive or semiconductive surface on which it is
placed; a precursor of the metallic material is
15 inserted within the said organic film placed on the
said surface at the same time as, or after, the step
consisting in placing the said organic film on the said
surface; and the said precursor of the metallic
material inserted within the said organic film is
20 converted into the said metallic material.

This process allows integrated circuits,
interconnects in microelectronics and microsystems to
be fabricated.

25 Figures 2a-2b